

Multi Project Wafer Schedule 2019/2020

X-CMOS 0.13 μm (*)

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XR013	25-Nov-2019	09-Dec-2019	17-Feb-2020
XR013	02-Mar-2020	13-Mar-2020	22-May-2020
XR013	02-Jun-2020	12-Jun-2020	21-Aug-2020
XR013	01-Sep-2020	11-Sep-2020	20-Nov-2020
XR013	09-Nov-2020	20-Nov-2020	29-Jan-2021

Additional runs available on request.

X-CMOS 0.18 μm (*)

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XH018	07-Nov-2019	14-Nov-2019	02-Apr-2020
XH018	27-Jan-2020	10-Feb-2020	22-Jun-2020
XH018	01-May-2020	15-May-2020	25-Sep-2020

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XH018	03-Aug-2020	17-Aug-2020	28-Dec-2020
XH018	06-Nov-2020	20-Nov-2020	02-Apr-2021

Available metal stack options for XH018 MPW runs:

4 Metal Layers: MET1-MET2-MET3-METMID; MIM or MIMH are optional capacitor modules

6 Metal Layers: MET1-MET2-MET3-MET4-METMID-METTHK; MIM or MIMH are optional capacitor modules

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XP018	17-Oct-2019	31-Oct-2019	05-Mar-2020
XP018	14-Feb-2020	28-Feb-2020	03-Jul-2020
XP018	26-Jun-2020	10-Jul-2020	13-Nov-2020
XP018	16-Oct-2020	30-Oct-2020	05-Mar-2021

Available metal options for XP018 MPW runs:

4 Metal Layers: MET1-MET2-MET3-METMID; MIM or MIMH are optional capacitor modules

6 Metal Layers: MET1-MET2-MET3-MET4-METMID-METTHK; MIM or MIMH are optional capacitor modules

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
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PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XT018	30-Aug-2019	13-Sep-2019	28-Feb-2020 **
XT018	15-Nov-2019	29-Nov-2019	15-May-2020 **
XT018	17-Jan-2020	31-Jan-2020	17-Jul-2020 **
XT018	30-Mar-2020	13-Apr-2020	28-Sep-2020 **
XT018	15-Jun-2020	29-Jun-2020	14-Dec-2020 **
XT018	31-Aug-2020	14-Sep-2020	01-Mar-2021 **
XT018	16-Nov-2020	30-Nov-2020	17-May-2021 **

****THKCOP module is not available for this MPW run.**

Available metal stack options for XT018 MPW runs:

4 Metal Layers: MET1-MET2-MET3-METTHK; MIMH as optional capacitor module

6 Metal Layers: MET1-MET2-MET3-MET4-METMID-METTHK; MIM or MIMH are optional capacitor modules

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XS018	18-Sep-2019	02-Oct-2019	05-Feb-2020 **
XS018	06-Mar-2020	20-Mar-2020	24-Jul-2020 **

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XS018	18-Sep-2020	02-Oct-2020	05-Feb-2021 **

****This MPW run covers only a restricted set of modules. Only limited LVT & PPD option will be offered. Please check with your X-FAB contact prior to tape-in.**

Available metal stack options for XS018 MPW runs:

4 Metal Layers: MET1-MET2-MET3-MET4-METTHIN; MIM23 or MIMH23 are optional capacitor modules

6 Metal Layers: MET1-MET2-MET3-MET4-MET5-METMID; MIM or MIMH are optional capacitor modules

X-CMOS 0.35 μm (*)

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XH035	15-Nov-2019	29-Nov-2019	29-Mar-2020
XH035	17-Jan-2020	31-Jan-2020	29-May-2020
XH035	08-May-2020	22-May-2020	18-Sep-2020
XH035	14-Aug-2020	28-Aug-2020	28-Dec-2020
XH035	13-Nov-2020	27-Nov-2020	29-Mar-2021

Additional runs available on request.

Usable modules: MOS, MOS5A, ISOMOS, THKOX, NMVMOS, PMVMOS, HVMOSMID, DEPL, BURDIF, CAPPOLY, HRPOLY, XRPOLY,

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
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TEEPROM, MIM, DMIM, METAL2, THKMET3, METAL4, THKMET, OTP, NHVETHK, PHVEMID, PHVETHK, NHVEMID

X-CMOS 0.6 μm (*)

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XC06	27-Mar-2020	10-Apr-2020	10-Jul-2020
XC06	04-Sep-2020	18-Sep-2020	18-Dec-2020

X-DIMOS 1.0 μm (*)

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XDH10/XDM10	06-Sep-2019	20-Sep-2019	06-Dec-2019
XDH10/XDM10	06-Mar-2020	20-Mar-2020	05-Jun-2020
XDH10/XDM10	04-Sep-2020	18-Sep-2020	04-Dec-2020

MEMS

PROCESS	TAPE-IN	DATA RELEASE	SAMPLES OUT
XMB10	12-Jun-2020	30-Jun-2020	31-October-2020